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SUB: Updated Documentation of Component Qualification; Reliability / Environmental / Physical, Mechanical & Process Tests

NTP Series - Surface Mount Polymer Cathode Low ESR Tantalum Chip Capacitors

- The following test data report covers NTP series family component qualification test data
- Product specification: http://www.niccomp.com/catalog/ntp.pdf
- NTP107M6.3TRA(25)F = 100uF / 6.3VDC / A case 3216 size / Lot #: 1302S701Z
- NTP157M10TRD(40)F = 150uF / 10VDC / D case 7343 size / Lot #: 1304S591Z

Reliability / Environmental Tests (test conditions, see page 2)

- High Temperature Life / n = 77
- Storage Life / n = 77
- Load Humidity / n = 77
- Temperature Cycle / n = 77
- Thermal Shock / n = 30
- Moisture Resistance / n = 77

Physical, Mechanical & Process Tests (test conditions, see page 2)

- Physical Dimensions / n = 30
- Terminal Strength / n = 30
- Resistance to Solvents / n = 5
- Solderability & Leaching / n = 60 (steam aged = 15 / dual temp reflow = 30 / leaching = 15)
- Resistance to Soldering Heat / n = 30

Results:

- All samples pass all Reliability / Environmental / Physical, Mechanical & Process Tests
- Components are qualified

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	Part Number>			NTP107M6.3TRA(25)F		NTP157M10TRD(40)F	
Test Name	Method Reference	Test Conditions	Sample Size (per lot)	Failure Count	Sample Size (per lot)	Failure Count	
Reliability and Environmental Test	S						
High Temperature Life	MIL-STD-202, Method 108	105°C, Rated Voltage, 2000 Hours.	77	0	77	0	
Storage Life	MIL-STD-202, Method 108	105°C, 0 Volts, 2000 Hours.	77	0	77	0	
Load Humidity	MIL-STD-202, Method 103	60°C, 90% RH, Rated Voltage, 1000 Hours.	77	0	77	0	
Temperature Cycle	JESD22, Method JA-104	-55°C to +105°C, 1000 Cycles.	77	0	77	0	
Thermal Shock	MIL-STD-202, Method 107	-55°C to +105°C, 1000 Cycles.	30	0	30	0	
Moisture Resistance	MIL-STD-202, Method 106	Cycled Temperature / RH, 0 Volts DC, 10 Cycles of 24 Hours.	77	0	77	0	
Physical, Mechanical, and Process	Tests						
Physical Dimensions	Per Specifications	Length, width, and thickness.	30	0	30	0	
Terminal Strength	JIS-C-6429	Force of 1.8 kg for 60 seconds.	30	0	30	0	
Resistance to Solvents	MIL-STD-202, Method 215	Include aqueous wash chemical, OKEM Clean or equivalent.	5	0	5	0	
Solderability	ANSI / J-STD-002	8 hr steam age @ 215°C	15	0	15	0	
		4 hr dry age 155°C followed by 235 and 260°C dips	30	0	30	0	
		Leaching @ 260°C dip	15	0	15	0	
Resistance to Soldering Heat	MIL-STD-202, Method 210	Condition B, single wave solder, procedure 2, no preheat.	30	0	30	0	

Results:

- All samples pass all Reliability / Environmental / Physical, Mechanical & Process Tests
- Component is qualified

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